

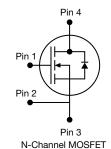
Vishay Siliconix

E Series Power MOSFET with Fast Body Diode

PRODUCT SUMMARY						
V _{DS} (V) at T _J max.	650					
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.123				
Q _g max. (nC)	120					
Q _{gs} (nC)	16					
Q _{gd} (nC)	33					
Configuration	Single					

PowerPAK[®] 8 x 8





FEATURES Completely lead (Pb)-free device

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and Halogen-free	SiHH26N60EF-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \degree C$, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V _{DS}	600	- V			
Gate-Source Voltage	V _{GS}	± 30	v			
Continuous Drain Current (T _J = 150 °C)	$V_{GS} \text{ at } 10 \text{ V} \qquad \frac{T_{C} = 25 \text{ °C}}{T_{C} = 100 \text{ °C}}$	۱ _D	24			
	$T_{\rm C} = 100 ^{\circ}{\rm C}$		15	А		
Pulsed Drain Current ^a	I _{DM}	67				
Linear Derating Factor		1.6	W/°C			
Single Pulse Avalanche Energy ^b	E _{AS}	353	mJ			
Maximum Power Dissipation	PD	202	W			
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	-55 to +150	°C			
Drain-Source Voltage Slope	T _J = 125 °C	dV/dt	70	V/ns		
Reverse Diode dV/dt ^c	uv/di	14	v/ns			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5 A.
- c. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.



COMPLIANT

HALOGEN FREE



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THERMAL RESISTANCE RATI	NGS								
PARAMETER	SYMBOL	TYP.		MAX.		UNIT			
Maximum Junction-to-Ambient	R _{thJA}	38 50			0044				
Maximum Junction-to-Case (Drain)	R _{thJC}	0.48 0.62				°C/W			
	•	•							
SPECIFICATIONS ($T_J = 25 \text{ °C}$, u	nless otherwi	se noted)							
PARAMETER	SYMBOL	-	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT	
Static					•	•			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 µA	600	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 10 mA	-	0.58	-	V/°C	
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	V_{GS} , $I_D = 2$	250 µA	2.0	-	4.0	V	
		١	/ _{GS} = ± 20	V	-	-	± 100	nA	
Gate-Source Leakage	I _{GSS}	N	/ _{GS} = ± 30	V	-	-	± 1	μA	
		V _{DS} =	480 V, V _G	_S = 0 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V	′, T _J = 125 °C	-	-	500	μA	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	ار	₀ = 13 A	-	0.123	0.141	Ω	
Forward Transconductance	9 _{fs}	V _{DS} :	= 30 V, I _D =	= 13 A	-	9.5	-	S	
Dynamic		•			•	•			
Input Capacitance	C _{iss}		$V_{GS} = 0 V$	_	-	2744	-		
Output Capacitance	C _{oss}	``	V _{DS} = 100 V	V,	-	126	-]	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	7	-	1		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0$ V to 480 V, $V_{GS} = 0$ V		-	82	-	pF		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	357	-	1		
Total Gate Charge	Qg				-	80	120	nC	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	I _D = 13 /	A, V _{DS} = 480 V	-	16	-		
Gate-Drain Charge	Q _{gd}				-	33	-		
Turn-On Delay Time	t _{d(on)}				-	25	50		
Rise Time	t _r	V _{DD} =	480 V, I _D :	= 13 A,	-	46	92	- ns	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	= 10 V, R _g =	= 9.1 Ω	-	93	140		
Fall Time	t _f				-	56	84		
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.3	0.6	1.2	Ω		
Drain-Source Body Diode Characteristic	cs								
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	24	А		
Pulsed Diode Forward Current	I _{SM}			-	-	67			
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 13 A	, V _{GS} = 0 V	-	0.9	1.2	V	
Reverse Recovery Time	t _{rr}			10.4	-	146	292	ns	
Reverse Recovery Charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 13 A, dl/dt = 100 A/ μ s, V _R = 25 V		-	0.9	1.8	μC		
Reverse Recovery Current	I _{RRM}			-	12	-	Α		

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

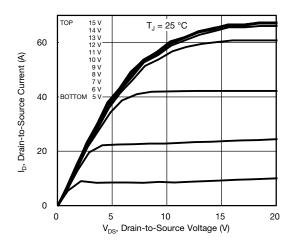


Fig. 1 - Typical Output Characteristics

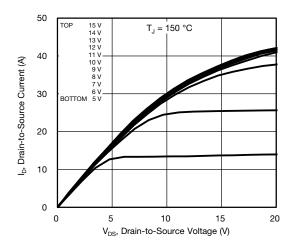
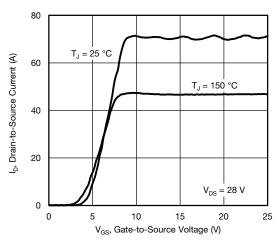
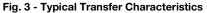


Fig. 2 - Typical Output Characteristics

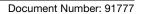




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3.0 13 / Drain-to-Source On-Resistance (Normalized) 2.5 2.0 1.5 1.0 10 V R_{DS(on)}, I 0.5 0 -40 -20 80 100 120 140 160 -60 0 20 40 60 T_J, Junction Temperature (°C)

Fig. 4 - Normalized On-Resistance vs. Temperature

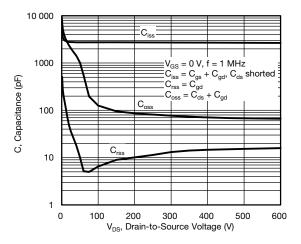
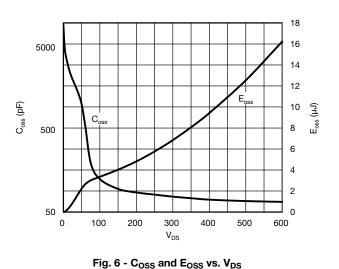


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage





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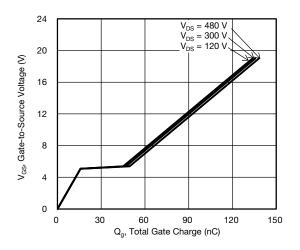


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

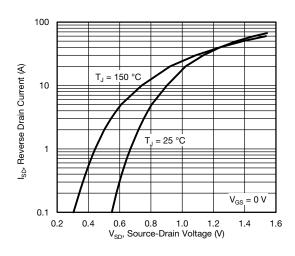
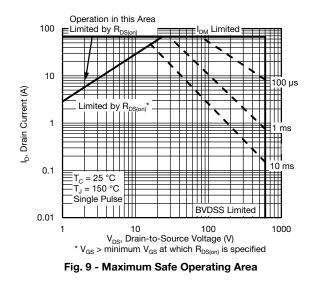


Fig. 8 - Typical Source-Drain Diode Forward Voltage



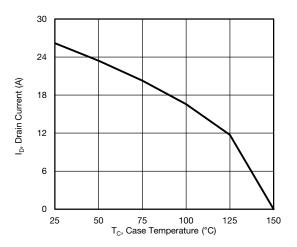


Fig. 10 - Maximum Drain Current vs. Case Temperature

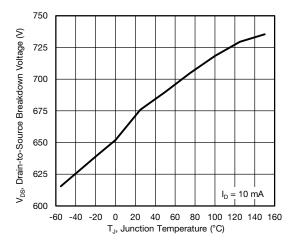


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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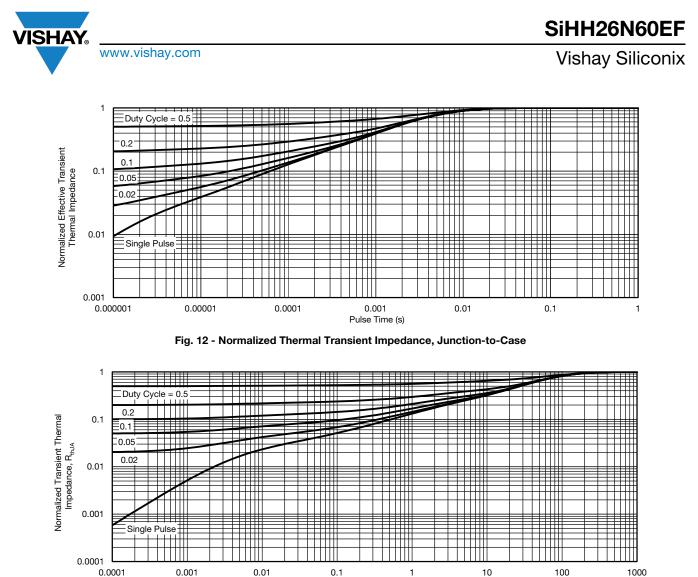


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

Pulse Time (s)

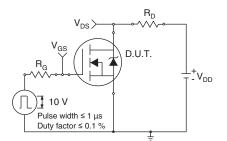


Fig. 14 - Switching Time Test Circuit

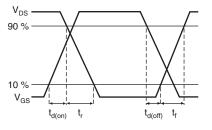


Fig. 15 - Switching Time Waveforms

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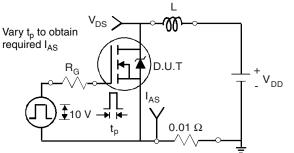
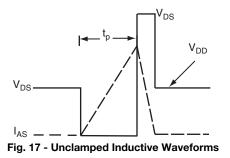


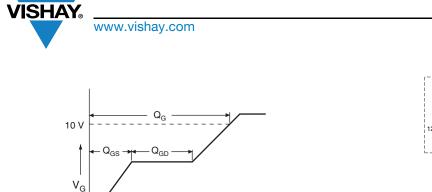
Fig. 16 - Unclamped Inductive Test Circuit

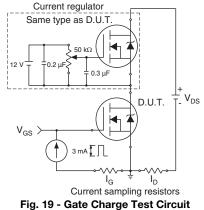


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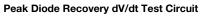




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Fig. 18 - Basic Gate Charge Waveform

Charge



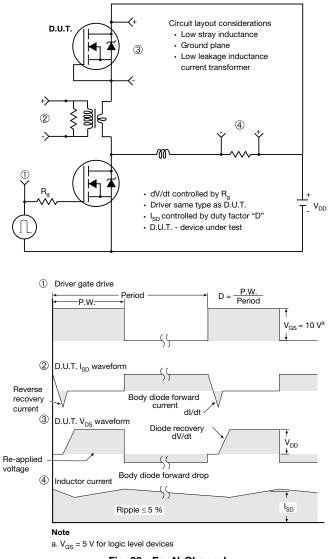


Fig. 20 - For N-Channel

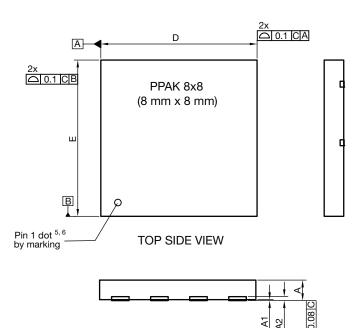
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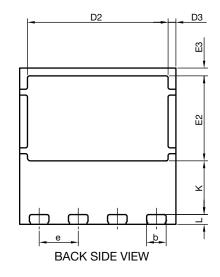
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PowerPAK[®] 8 x 8 Case Outline





DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
A ⁸	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.			0.008 ref.		
b ⁴	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3		0.40 BSC			0.016 BSC		
e	2.00 BSC		0.079 BSC				
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3	0.40 BSC			0.40 BSC 0.016 BSC			
К	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ³	8				8		

D

Notes

1. Use millimeters as the primary measurement.

2. Dimensioning and tolerances conform to ASME Y14.5 M - 1994.

3. N is the number of terminals.

4. Package warpage max. 0.08 mm.

5. The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body.

6. Exact shape and size of this feature is optional.

ECN: T15-0225-Rev. A, 18-May-15 DWG: 6041

Revision: 18-May-15

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Recommended Minimum PADs for PowerPAK[®] 8 mm x 8 mm



Dimensions in millimeters

Document Number: 68441



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